H&M 华之美半导体 SEMI www.hmsemi.com 322X_{FU}/Õ47X_{I U}/95C*堠+'P/Ej cppgdGpj c pego gpv'O qf g'O QUHGV''

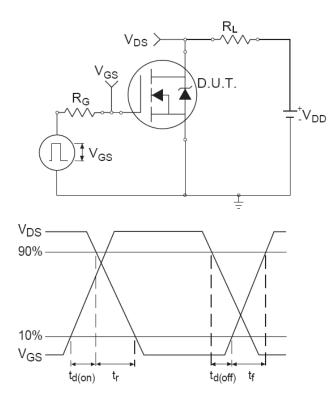
Features

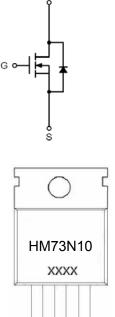
- $V_{DSS}=100V/V_{GSS}=\pm 25V/I_D=73A$ $R_{DS(ON)}=12m\Omega(max.)@V_{GS}=10V$
- Low Dense Cell Design
- Reliable and Rugged
- Advanced trench process technology

Applications

- Synchronous Rectification
- Power Management in Inverter System

Switching Time Test Circuit and Waveforms





Pin Description

Marking and pin Assignment



TO-220-3L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM73N10	HM73N10	TO-220-3L	-	-	-

Electrical Characteristics of CP Test (TA=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур	Max.	Unit
Static Chai	racteristics			_	-	
$\mathrm{BV}_{\mathrm{DSS}}$	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D =250uA	100			V
T	Zero Gate Voltage Drain Current	V_{DS} =80V, V_{GS} =0V			1	
I _{DSS}		T _J =85°0	C		30	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250uA	2	2.8	4	V
I _{GSS}	Gate Leakage Current	V_{GS} =±25V, V_{DS} =0V			±100	nA
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =10V, I _D =40A		10	12	mΩ
V_{SD}	Diode Forward Voltage	I_{SD} =30A, V_{GS} =0V			1.3	V
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Frequency=1MHz		1.2		Ω

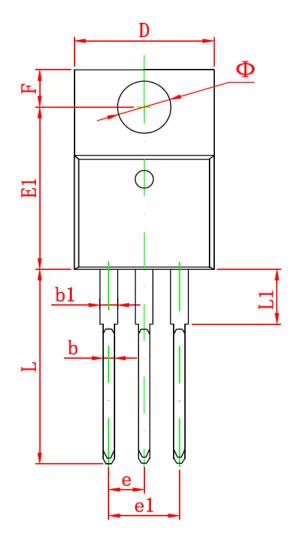
""""Note: 1: Pulse test ; pulse width \leq 300ns, duty cycle \leq 2%.

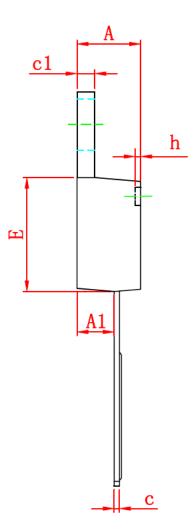
""2: Guaranteed by design, not subject to production testing.

H&M 华之美半导体 SEMI www.hmsemi.com **JO 95P 32**

 $322 X_{\rm FU} \not \sim \tilde{0}47 X_{\rm I~U} \not \sim 95 C^* K_{\rm F} + 'P/E j~cppgriGpj~c~pego~gpv'O~qf~g'O~QUHGV''$

TO-220-3L PACKAGE OUTLINE DIMENSIONS





Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Мах	Min	Мах	
A	4.470	4.670	0.176	0.184	
A1	2.520	2.820	0.099	0.111	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
с	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
E1	12.060	12.460	0.475	0.491	
е	2.540) TYP	0.100 TYP		
e1	4.980	5.180	0.196	0.204	
F	2.590	2.890	0.102	0.114	
h	0.000	0.300	0.000	0.012	
L	13.400	13.800	0.528	0.543	
L1	3.560	3.960	0.140	0.156	
Ф	3.735	3.935	0.147	0.155	

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